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LOC

DIST

AA

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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	E2	REVISED PER ECO-11-005033	26MAR11	RK	HMR

16
[.63]

POSITION 1

HOUSING

2.54
[.10]
NOMINAL

1.27
[.05]
NOMINAL

11.43
[.45]
NOMINAL

LED TERMINAL
QUANTITY 4

POSITION 2

2

21.34
[.840]

30°

FRONT SHIELD

2.29
[.09]

15.85
[.624]
MAXIMUM

13.64
[.537]

REAR SHIELD

2.79
[.11]

4.06
[.16]

TERMINAL
QUANTITY 8

3.56
[.14]

1.52
[.06]
TYP

2.79
[.11]
TYP

3.05
[.12]
2 PLACES

2.54
[.10]
TYP

10.8
[.425]
2 PLACES

6.35
[.25]
TYP

16.51
[.650]

14.48^{+0.38}_{-0.00}
[.570^{+0.015}_{-0.000}]

TOP OF PC BOARD

0.25
[.010]

SUGGESTED PANEL CUTOUT

2.03±0.05
[.080±.002]
2 PLACES

11.43±0.05
[.450±.002]

10.16±0.05
[.400±.002]

2.54±0.05
[.100±.002]
TYPICAL

1.27±0.05
[.050±.002]
TYPICAL

φ1.57±0.08
[.062±.003]
2 PLACES

3.05±0.05
[.120±.002]

φ3.25±0.08/-0.05
[.128+.003/-0.002]
2 PLACES

ANODE(+)
2 PLACES

10.13±0.05
[.399±.002]

10.13±0.05
[.399±.002]

0.58±0.05
[.023±.002]

2.54±0.05
[.100±.002]

4.32±0.05
[.170±.002]

2.79±0.05
[.110±.002]

6.35±0.05
[.250±.002]

2.54±0.05
[.100±.002]

φ0.89±0.08
[.035±.003]
8 PLACES

φ1.19±0.08
[.047±.003]
4 PLACES

SUGGESTED PC BOARD LAYOUT

COMPONENT SIDE

SCALE 4:1

1. MATERIAL: HOUSING – PBT THERMOPLASTIC BLACK, UL94V-0.
TERMINALS – 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27μm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81μm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS – 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27μm[.000050] MINIMUM NICKEL AND 2.03 μm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

LIGHT EMITTING DIODE (LED) – DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μm[.0003500] THICK Sn/Cu OVER 2.03 μm[.000080] THICK Ag OVER 1.02μm[.000040] THICK Cu OVER 3.56 μm[.000140] THICK Ni OVER 1.02μm[.000040] Cu UNDERPLATE

2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.

3. USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.

4. THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.

1	YELLOW	GREEN	5569564-5
1	GREEN	GREEN	5569564-4
1	GREEN	YELLOW	5569564-1
MATERIAL	POSITION 1	POSITION 2	PART NUMBER
	LED COLOR		

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS:
mm [INCHES]

0 PLC ± -

1 PLC ± -

2 PLC ± 0.25[.01]

3 PLC ± 0.13[.005]

4 PLC ± -

ANGLES ± -

FINISH

TOLERANCES UNLESS OTHERWISE SPECIFIED:

0 PLC ± -

1 PLC ± -

2 PLC ± 0.25[.01]

3 PLC ± 0.13[.005]

4 PLC ± -

ANGLES ± -

FINISH

DWN L. VARELA - 07JUN2005

CHK J. WESTMAN 07JUN2005

APVD S. FLICKINGER 07JUN2005

PRODUCT SPEC 108-1163

APPLICATION SPEC 114-2154

WEIGHT -

CUSTOMER DRAWING

TE Connectivity

MODULAR JACK ASSEMBLY,
8 POSITION, RIGHT ANGLE, LOW PROFILE,
PANEL GROUND WITH LEDS

SIZE A2

CAGE CODE 00779

DRAWING NO C=5569564

RESTRICTED TO -

SCALE 2:1

SHEET 1 of 1

REV E2

1471-9 (3/11)

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[5569564-5](#)